

IRF7526D1

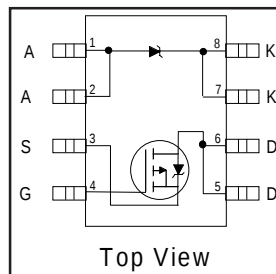
FETKY™ MOSFET & Schottky Diode

- Co-packaged HEXFET® Power MOSFET and Schottky Diode
- P-Channel HEXFET
- Low V_F Schottky Rectifier
- Generation 5 Technology
- Micro8™ Footprint

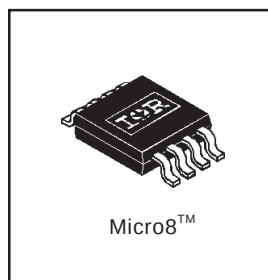
Description

The **FETKY™** family of co-packaged HEXFETs and Schottky diodes offer the designer an innovative board space saving solution for switching regulator applications. Generation 5 HEXFETs utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. Combining this technology with International Rectifier's low forward drop Schottky rectifiers results in an extremely efficient device suitable for use in a wide variety of portable electronics applications like cell phone, PDA, etc.

The new Micro8™ package, with half the footprint area of the standard SO-8, provides the smallest footprint available in an SOIC outline. This makes the Micro8™ an ideal device for applications where printed circuit board space is at a premium. The low profile (<1.1mm) of the Micro8™ will allow it to fit easily into extremely thin application environments such as portable electronics and PCMCIA cards.



$V_{DSS} = -30V$
$R_{DS(on)} = 0.20\Omega$
Schottky $V_f = 0.39V$



Absolute Maximum Ratings

Parameter	Maximum	Units
I_D @ $T_A = 25^\circ C$	-2.0	A
I_D @ $T_A = 70^\circ C$	-1.6	
I_{DM}	-16	
P_D @ $T_A = 25^\circ C$	1.25	W
P_D @ $T_A = 70^\circ C$	0.8	
	10	mW/°C
V_{GS}	± 20	V
dv/dt	-5.0	V/ns
T_J, T_{STG}	-55 to +150	°C

Thermal Resistance Ratings

Parameter	Maximum	Units
$R_{\theta JA}$	100	°C/W

Notes:

- ① Repetitive rating – pulse width limited by max. junction temperature (see Fig. 9)
- ② $I_{SD} \leq -1.2A$, $di/dt \leq 160A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150^\circ C$
- ③ Pulse width $\leq 300\mu s$ – duty cycle $\leq 2\%$
- ④ When mounted on 1 inch square copper board to approximate typical multi-layer PCB thermal resistance

MOSFET Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-30	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	0.17	0.20	Ω	$V_{GS} = -10V, I_D = -1.2A$ ③
		—	0.30	0.40		$V_{GS} = -4.5V, I_D = -0.60A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	-1.0	—	—	V	$V_{DS} = V_{GS}, I_D = -250\mu A$
g_{fs}	Forward Transconductance	0.94	—	—	S	$V_{DS} = -10V, I_D = -0.60A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	-1.0	μA	$V_{DS} = -24V, V_{GS} = 0V$
		—	—	-25		$V_{DS} = -24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{GS} = -20V$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{GS} = 20V$
Q_g	Total Gate Charge	—	7.5	11	nC	$I_D = -1.2A$
Q_{gs}	Gate-to-Source Charge	—	1.3	1.9		$V_{DS} = -24V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	2.5	3.7		$V_{GS} = -10V$, See Fig. 6 ③
$t_{d(on)}$	Turn-On Delay Time	—	9.7	—	ns	$V_{DD} = -15V$
t_r	Rise Time	—	12	—		$I_D = -1.2A$
$t_{d(off)}$	Turn-Off Delay Time	—	19	—		$R_G = 6.2\Omega$
t_f	Fall Time	—	9.3	—		$R_D = 12\Omega$, ③
C_{iss}	Input Capacitance	—	180	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	87	—		$V_{DS} = -25V$
C_{rss}	Reverse Transfer Capacitance	—	42	—		$f = 1.0\text{MHz}$, See Fig. 5

MOSFET Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-1.25	A	
I_{SM}	Pulsed Source Current (Body Diode)	—	—	-9.6		
V_{SD}	Body Diode Forward Voltage	—	—	-1.2	V	$T_J = 25^\circ\text{C}, I_S = -1.2A, V_{GS} = 0V$
t_{rr}	Reverse Recovery Time (Body Diode)	—	30	45	ns	$T_J = 25^\circ\text{C}, I_F = -1.2A$
Q_{rr}	Reverse Recovery Charge	—	37	55	nC	$di/dt = 100A/\mu s$ ③

Schottky Diode Maximum Ratings

	Parameter	Max.	Units	Conditions
$I_{F(av)}$	Max. Average Forward Current	1.9	A	50% Duty Cycle. Rectangular Wave, $T_A = 25^\circ\text{C}$ See Fig. 14 $T_A = 70^\circ\text{C}$
		1.3		
I_{SM}	Max. peak one cycle Non-repetitive Surge current	120	A	5 μs sine or 3 μs Rect. pulse
		11		10ms sine or 6ms Rect. pulse

Following any rated load condition & with V_{RRM} applied

Schottky Diode Electrical Specifications

	Parameter	Max.	Units	Conditions
V_{FM}	Max. Forward voltage drop	0.50	V	$I_F = 1.0A, T_J = 25^\circ\text{C}$
		0.62		$I_F = 2.0A, T_J = 25^\circ\text{C}$
		0.39		$I_F = 1.0A, T_J = 125^\circ\text{C}$
		0.57		$I_F = 2.0A, T_J = 125^\circ\text{C}$
I_{RM}	Max. Reverse Leakage current	0.06	mA	$V_R = 30V, T_J = 25^\circ\text{C}$
		16		$T_J = 125^\circ\text{C}$
C_t	Max. Junction Capacitance	92	pF	$V_R = 5Vdc$ (100kHz to 1 MHz) 25°C
dv/dt	Max. Voltage Rate of Charge	3600	V/ μs	Rated V_R

(HEXFET is the reg. TM for International Rectifier Power MOSFET's)

Power Mosfet Characteristics

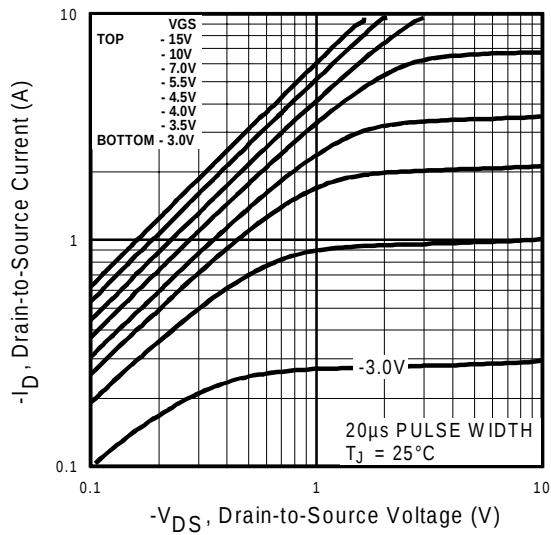


Fig 1. Typical Output Characteristics

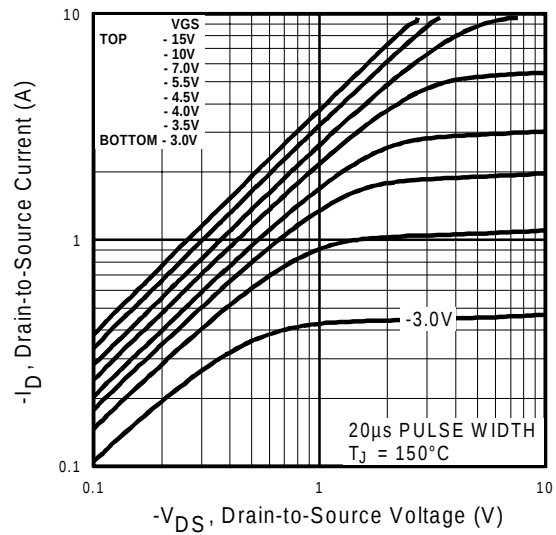


Fig 2. Typical Output Characteristics

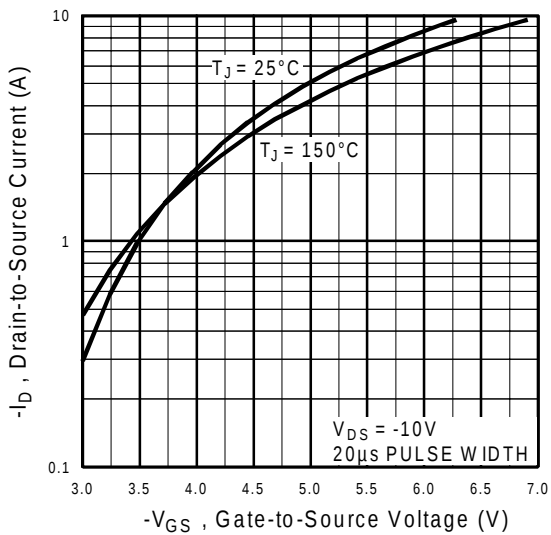


Fig 3. Typical Transfer Characteristics

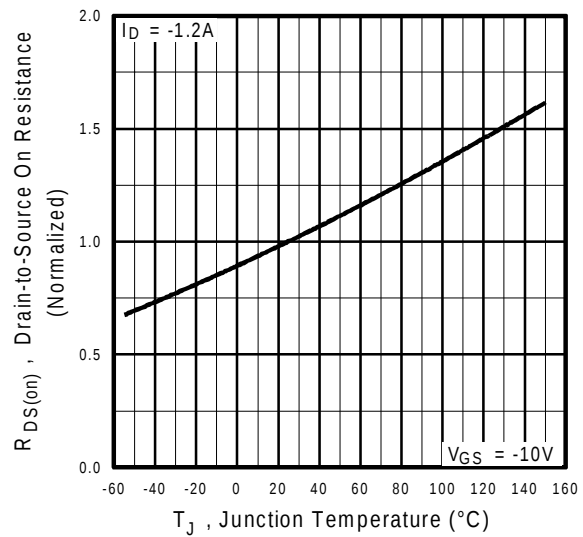
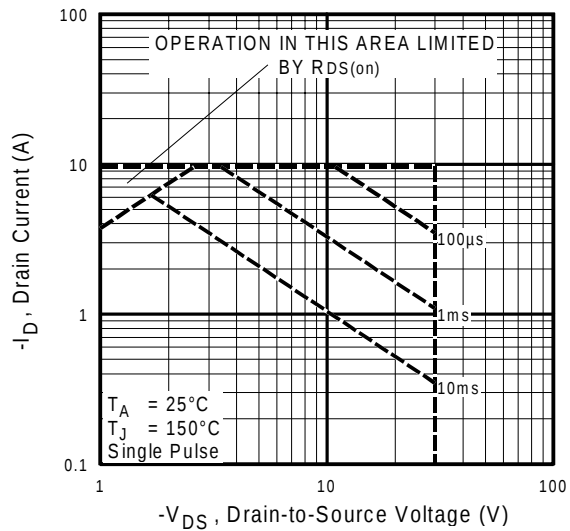
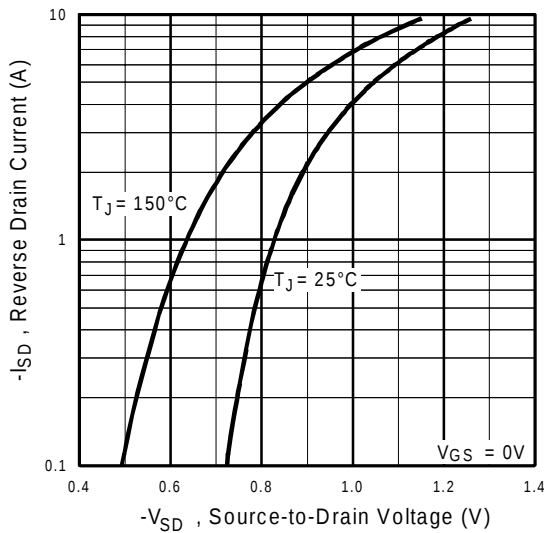
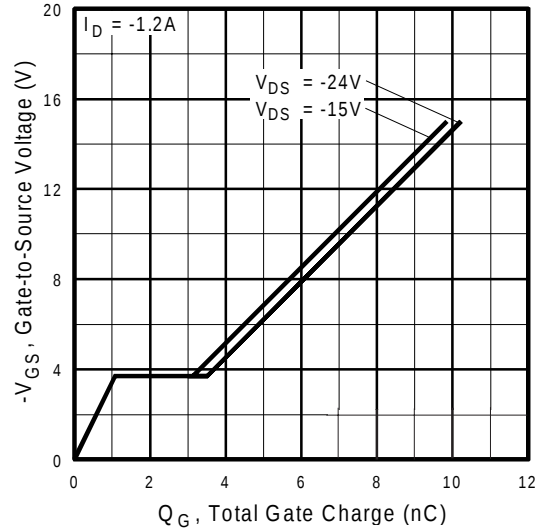
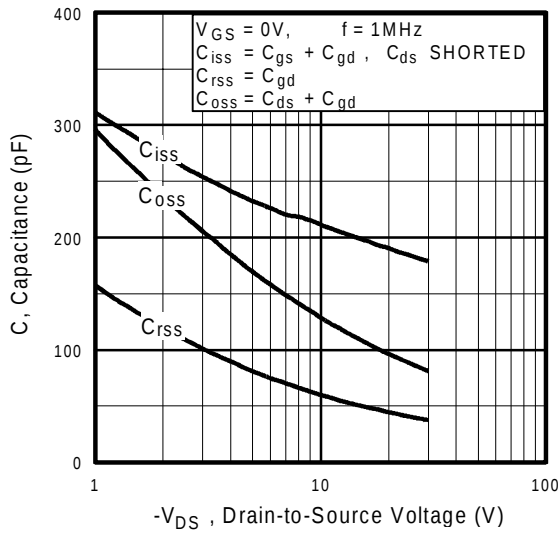


Fig 4. Normalized On-Resistance
Vs. Temperature

Power Mosfet Characteristics



Power Mosfet Characteristics

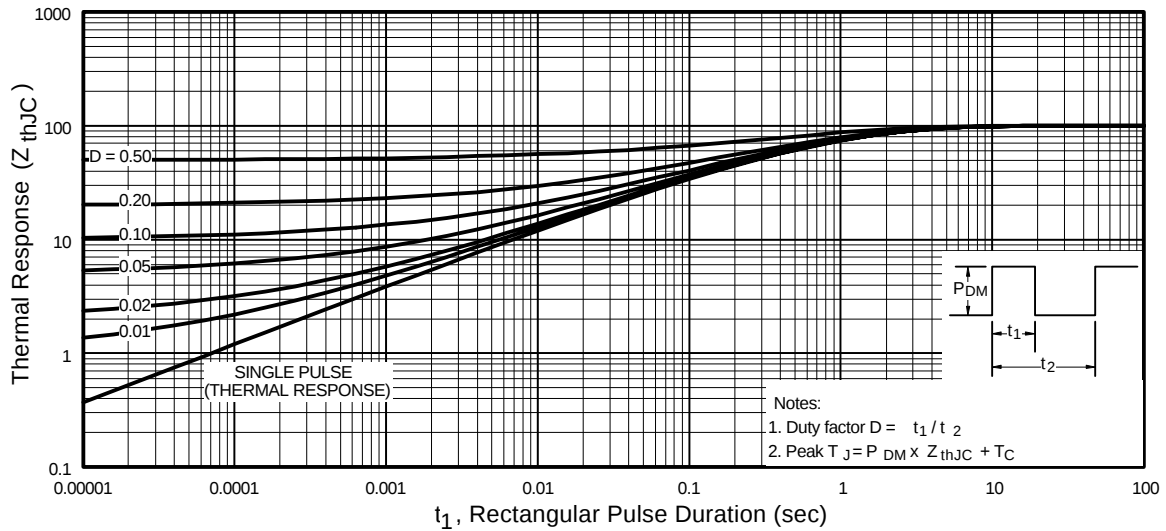


Fig 9. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

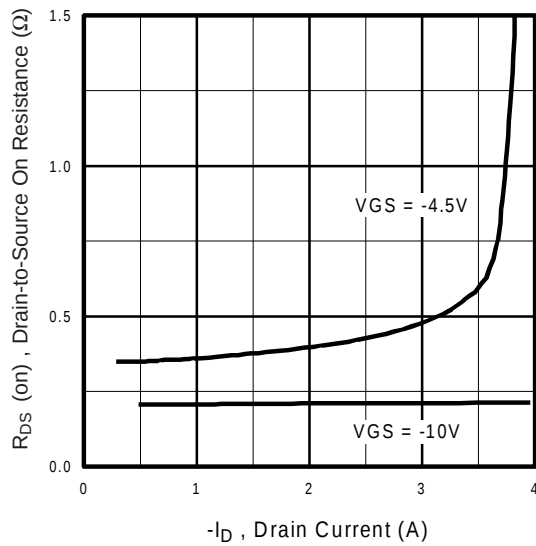


Fig 10. Typical On-Resistance Vs. Drain Current

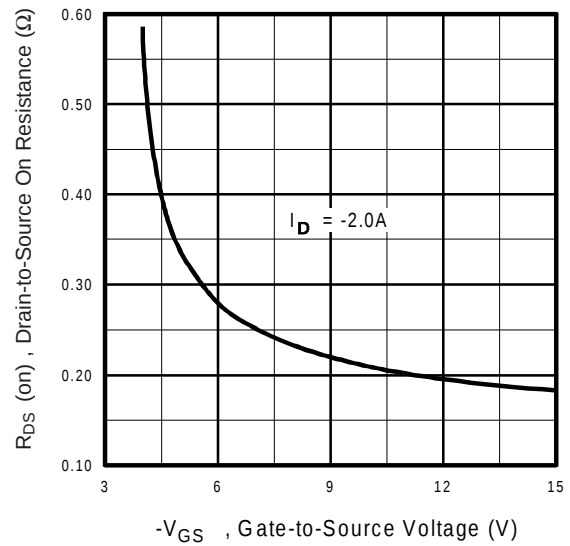


Fig 11. Typical On-Resistance Vs. Gate Voltage

Schottky Diode Characteristics

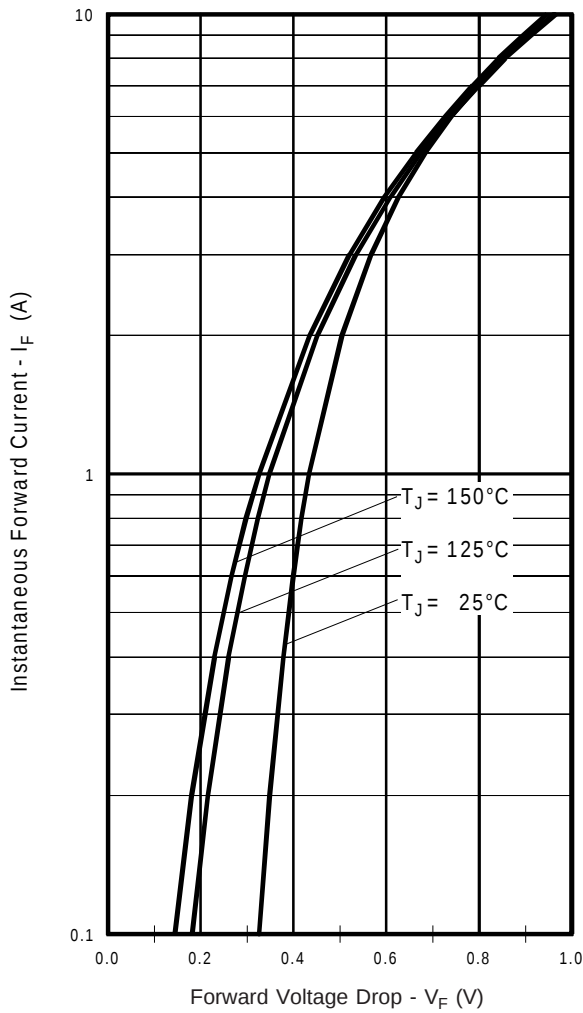


Fig. 12 -Typical Forward Voltage Drop Characteristics

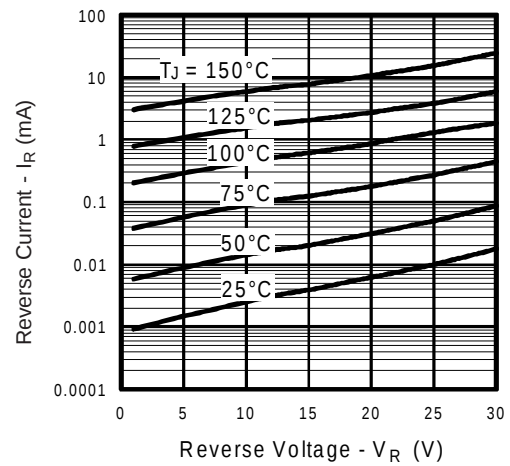


Fig. 13 - Typical Values of Reverse Current Vs. Reverse Voltage

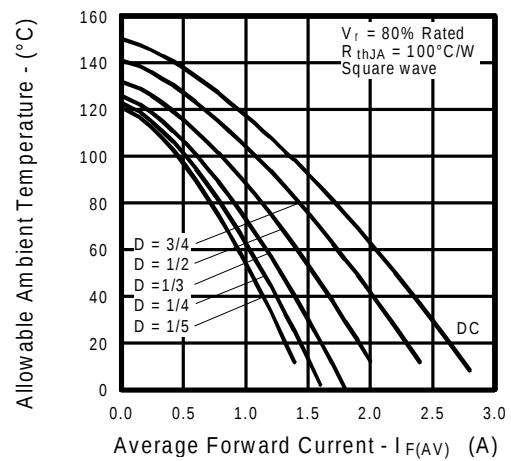
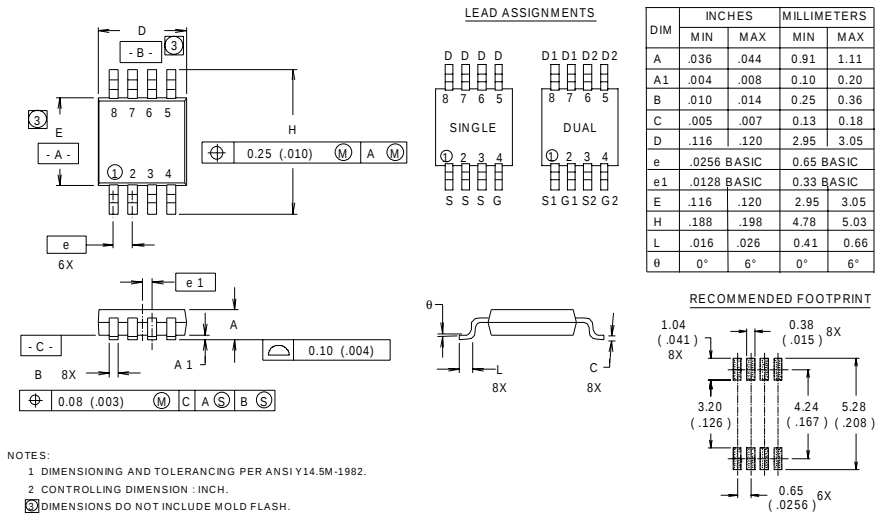
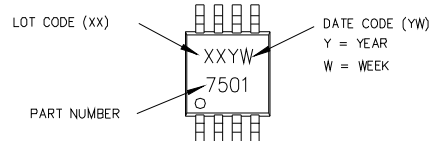


Fig.14 - Maximum Allowable Ambient Temp. Vs. Forward Current



Part Marking

EXAMPLE: THIS IS AN IRF7501



WW = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR

DATE CODE EXAMPLES:

YWW = 9503 = 5C
 YWW = 9532 = EF

YEAR	Y	WORK WEEK	W
2001	1	01	A
2002	2	02	B
2003	3	03	C
1994	4	04	D
1995	5		
1996	6		
1997	7		
1998	8		
1999	9		
2000	D	24	X
		25	Y
		26	Z

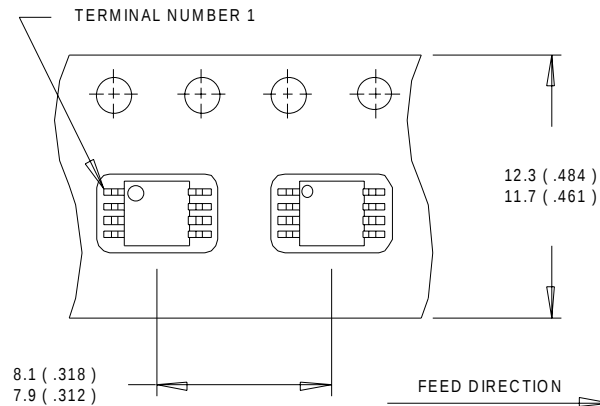
WW = (27-52) IF PRECEDED BY A LETTER

YEAR	Y	WORK WEEK	W
2001	A	27	A
2002	B	28	B
2003	C	29	C
1994	D	30	D
1995	E		
1996	F		
1997	G		
1998	H		
1999	J		
2000	K	50	X
		51	Y
		52	Z

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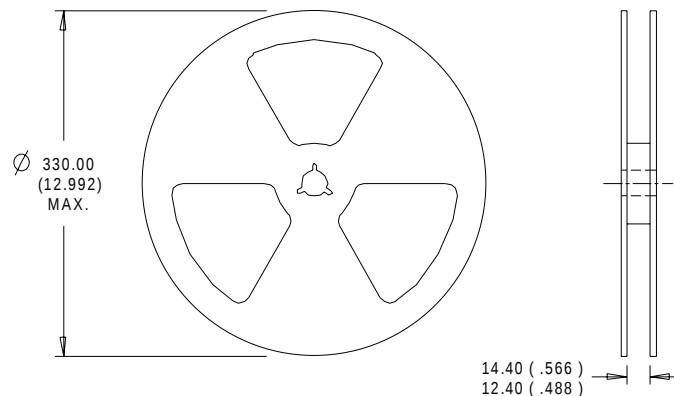
International
IR Rectifier

Micro8™ Tape & Reel



NOTES:

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.
2. CONTROLLING DIMENSION : MILLIMETER.



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1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

International
IR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331

IR GREAT BRITAIN: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

IR CANADA: 15 Lincoln Court, Brampton, Ontario L6T3Z2, Tel: (905) 453 2200

IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo Japan 171 Tel: 81 3 3983 0086

IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994 Tel: ++ 65 221 8371

IR TAIWAN: 16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan Tel: 886-2-2377-9936

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Data and specifications subject to change without notice . 5/99

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